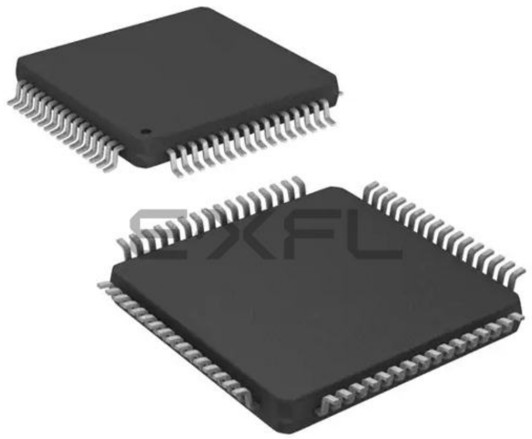

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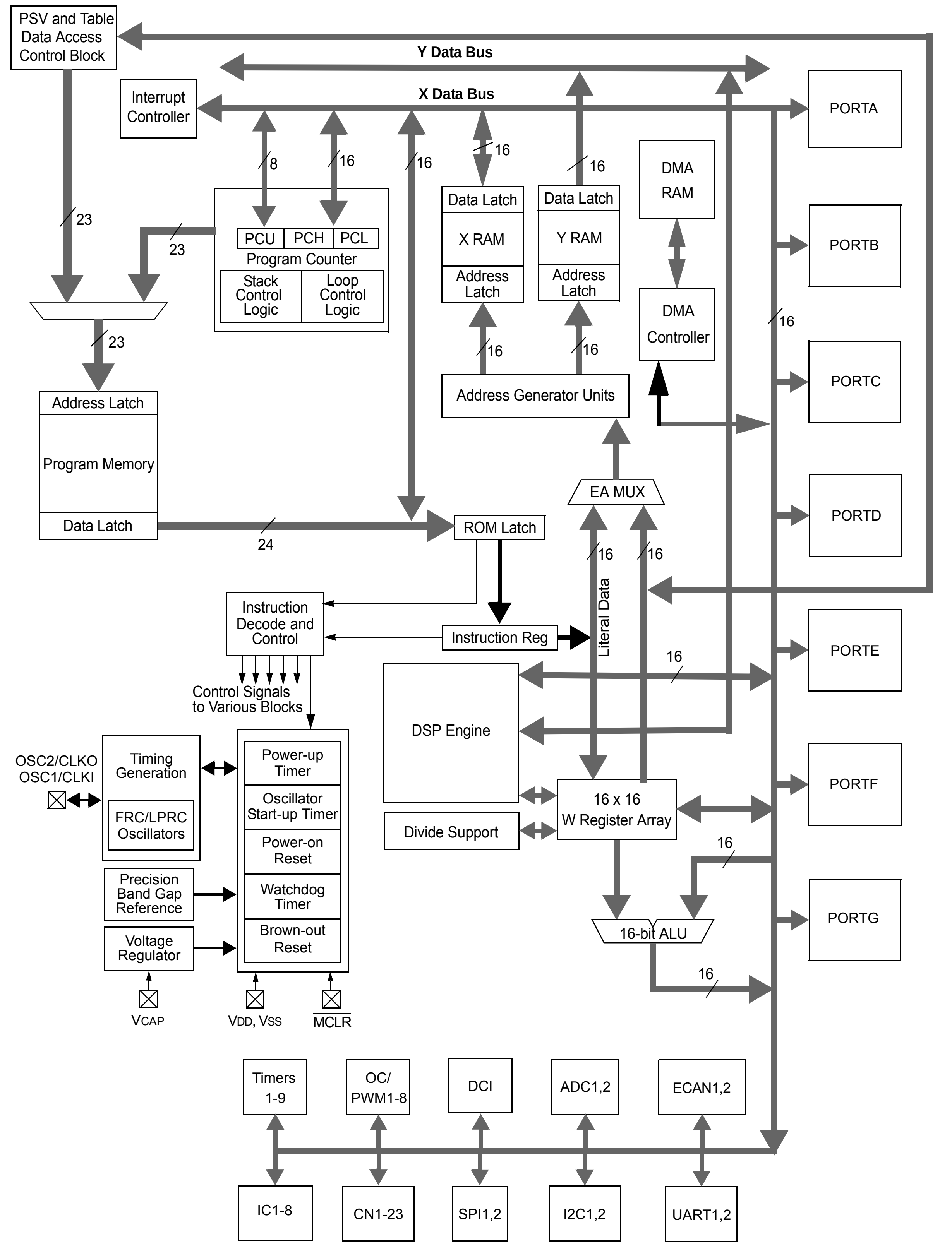
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp306at-i-pt

FIGURE 1-1: dsPIC33FJXXXGPX06A/X08A/X10A GENERAL BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See the **"Pin Diagrams"** section for the specific pins and features present on each device.

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT(1)	DL<2:0>		
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clear only bit		
R = Readable bit	W = Writable bit	-n = Value at POR	‘1’ = Bit is set
0’ = Bit is cleared	‘x = Bit is unknown	U = Unimplemented bit, read as ‘0’	

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **US:** DSP Multiply Unsigned/Signed Control bit
1 = DSP engine multiplies are unsigned
0 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1)
1 = Terminate executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits
111 = 7 DO loops active
•
•
•
001 = 1 DO loop active
000 = 0 DO loops active

bit 7 **SATA:** AccA Saturation Enable bit
1 = Accumulator A saturation enabled
0 = Accumulator A saturation disabled

bit 6 **SATB:** AccB Saturation Enable bit
1 = Accumulator B saturation enabled
0 = Accumulator B saturation disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit
1 = Data space write saturation enabled
0 = Data space write saturation disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU interrupt priority level is greater than 7
0 = CPU interrupt priority level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space visible in data space
0 = Program space not visible in data space

bit 1 **RND:** Rounding Mode Select bit
1 = Biased (conventional) rounding enabled
0 = Unbiased (convergent) rounding enabled

bit 0 **IF:** Integer or Fractional Multiplier Mode Select bit
1 = Integer mode enabled for DSP multiply ops
0 = Fractional mode enabled for DSP multiply ops

Note 1: This bit will always read as ‘0’.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

3.5 Arithmetic Logic Unit (ALU)

The dsPIC33FJXXXGPX06A/X08A/X10A ALU is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are 2's complement in nature. Depending on the operation, the ALU may affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as Borrow and Digit Borrow bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array, or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157) for information on the SR bits affected by each instruction.

The dsPIC33FJXXXGPX06A/X08A/X10A CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit-divisor division.

3.5.1 MULTIPLIER

Using the high-speed 17-bit x 17-bit multiplier of the DSP engine, the ALU supports unsigned, signed or mixed-sign operation in several MCU multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.5.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

- 32-bit signed/16-bit signed divide
- 32-bit unsigned/16-bit unsigned divide
- 16-bit signed/16-bit signed divide
- 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. 16-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.6 DSP Engine

The DSP engine consists of a high-speed, 17-bit x 17-bit multiplier, a barrel shifter and a 40-bit adder/subtracter (with two target accumulators, round and saturation logic).

The dsPIC33FJXXXGPX06A/X08A/X10A is a single-cycle, instruction flow architecture; therefore, concurrent operation of the DSP engine with MCU instruction flow is not possible. However, some MCU ALU and DSP engine resources may be used concurrently by the same instruction (e.g., ED, EDAC).

The DSP engine also has the capability to perform inherent accumulator-to-accumulator operations which require no additional data. These instructions are `ADD`, `SUB` and `NEG`.

The DSP engine has various options selected through various bits in the CPU Core Control register (CORCON), as listed below:

- Fractional or integer DSP multiply (IF)
- Signed or unsigned DSP multiply (US)
- Conventional or convergent rounding (RND)
- Automatic saturation on/off for AccA (SATA)
- Automatic saturation on/off for AccB (SATB)
- Automatic saturation on/off for writes to data memory (SATDW)
- Accumulator Saturation mode selection (ACCSAT)

Table 3-1 provides a summary of DSP instructions. A block diagram of the DSP engine is shown in Figure 3-3.

TABLE 3-1: DSP INSTRUCTIONS SUMMARY

Instruction	Algebraic Operation	ACC Write Back
`CLR`	$A = 0$	Yes
`ED`	$A = (x - y)^2$	No
`EDAC`	$A = A + (x - y)^2$	No
`MAC`	$A = A + (x \bullet y)$	Yes
`MAC`	$A = A + x2$	No
`MOVSAC`	No change in A	Yes
`MPY`	$A = x \bullet y$	No
`MPY`	$A = x^2$	No
`MPY.N`	$A = -x \bullet y$	No
`MSC`	$A = A - x \bullet y$	Yes

TABLE 4-21: ECAN2 REGISTER MAP WHEN C2CTRL1.WIN = 0 OR 1 FOR dsPIC33FJXXXGP706A/708A/710A DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C2CTRL1	0500	—	—	CSIDL	ABAT	—	REQOP<2:0>			OPMODE<2:0>			—	CANCAP	—	—	WIN	0480
C2CTRL2	0502	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C2VEC	0504	—	—	—	FILHIT<4:0>					—	ICODE<6:0>							0000
C2FCTRL	0506	DMABS<2:0>			—	—	—	—	—	—	—	—	FSA<4:0>					0000
C2FIFO	0508	—	—	FBP<5:0>						—	—	FNRB<5:0>						0000
C2INTF	050A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C2INTE	050C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C2EC	050E	TERRCNT<7:0>								RERRCNT<7:0>								0000
C2CFG1	0510	—	—	—	—	—	—	—	—	SJW<1:0>		BRP<5:0>						0000
C2CFG2	0512	—	WAKFIL	—	—	—	SEG2PH<2:0>			SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			0000
C2FEN1	0514	FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8	FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0	FFFF
C2FMSKSEL1	0518	F7MSK<1:0>		F6MSK<1:0>		F5MSK<1:0>		F4MSK<1:0>		F3MSK<1:0>		F2MSK<1:0>		F1MSK<1:0>		F0MSK<1:0>		0000
C2FMSKSEL2	051A	F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>		F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN2 REGISTER MAP WHEN C2CTRL1.WIN = 0 FOR dsPIC33FJXXXGP706A/708A/710A DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0500-051E	**See definition when WIN = x**																
C2RXFUL1	0520	RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8	RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0	0000
C2RXFUL2	0522	RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24	RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16	0000
C2RXOVF1	0528	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF09	RXOVF08	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0	0000
C2RXOVF2	052A	RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24	RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16	0000
C2TR01CON	0530	TXEN1	TX ABAT1	TX LARB1	TX ERR1	TX REQ1	RTREN1	TX1PRI<1:0>		TXEN0	TX ABAT0	TX LARB0	TX ERR0	TX REQ0	RTREN0	TX0PRI<1:0>		0000
C2TR23CON	0532	TXEN3	TX ABAT3	TX LARB3	TX ERR3	TX REQ3	RTREN3	TX3PRI<1:0>		TXEN2	TX ABAT2	TX LARB2	TX ERR2	TX REQ2	RTREN2	TX2PRI<1:0>		0000
C2TR45CON	0534	TXEN5	TX ABAT5	TX LARB5	TX ERR5	TX REQ5	RTREN5	TX5PRI<1:0>		TXEN4	TX ABAT4	TX LARB4	TX ERR4	TX REQ4	RTREN4	TX4PRI<1:0>		0000
C2TR67CON	0536	TXEN7	TX ABAT7	TX LARB7	TX ERR7	TX REQ7	RTREN7	TX7PRI<1:0>		TXEN6	TX ABAT6	TX LARB6	TX ERR6	TX REQ6	RTREN6	TX6PRI<1:0>		xxxx
C2RXD	0540	Recieved Data Word																xxxx
C2TXD	0542	Transmit Data Word																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. It is important to realize that the address boundaries check for addresses less than, or greater than, the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes may, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected effective address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the effective address. When an address offset (e.g., [W7+W2]) is used, Modulo Address correction is performed but the contents of the register remain unchanged.

4.5 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data re-ordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which may be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.5.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when:

1. BWM bits (W register selection) in the MODCON register are any value other than ‘15’ (the stack cannot be accessed using Bit-Reversed Addressing).
2. The BREN bit is set in the XBREV register.
3. The addressing mode used is Register Indirect with Pre-Increment or Post-Increment.

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last ‘N’ bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Address modifier, or ‘pivot point’, which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is only executed for Register Indirect with Pre-Increment or Post-Increment Addressing and word sized data writes. It will not function for any other addressing mode or for byte sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing should not be enabled together. In the event that the user attempts to do so, Bit-Reversed Addressing will assume priority when active for the X WAGU and X WAGU Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN bit (XBREV<15>), a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the bit-reversed pointer.

TABLE 7-1: INTERRUPT VECTORS (CONTINUED)

Vector Number	Interrupt Request (IRQ) Number	IVT Address	AIVT Address	Interrupt Source
54	46	0x000070	0x000170	DMA4 – DMA Channel 4
55	47	0x000072	0x000172	T6 – Timer6
56	48	0x000074	0x000174	T7 – Timer7
57	49	0x000076	0x000176	SI2C2 – I2C2 Slave Events
58	50	0x000078	0x000178	MI2C2 – I2C2 Master Events
59	51	0x00007A	0x00017A	T8 – Timer8
60	52	0x00007C	0x00017C	T9 – Timer9
61	53	0x00007E	0x00017E	INT3 – External Interrupt 3
62	54	0x000080	0x000180	INT4 – External Interrupt 4
63	55	0x000082	0x000182	C2RX – ECAN2 Receive Data Ready
64	56	0x000084	0x000184	C2 – ECAN2 Event
65	57	0x000086	0x000186	Reserved
66	58	0x000088	0x000188	Reserved
67	59	0x00008A	0x00018A	DCIE – DCI Error
68	60	0x00008C	0x00018C	DCID – DCI Transfer Done
69	61	0x00008E	0x00018E	DMA5 – DMA Channel 5
70	62	0x000090	0x000190	Reserved
71	63	0x000092	0x000192	Reserved
72	64	0x000094	0x000194	Reserved
73	65	0x000096	0x000196	U1E – UART1 Error
74	66	0x000098	0x000198	U2E – UART2 Error
75	67	0x00009A	0x00019A	Reserved
76	68	0x00009C	0x00019C	DMA6 – DMA Channel 6
77	69	0x00009E	0x00019E	DMA7 – DMA Channel 7
78	70	0x0000A0	0x0001A0	C1TX – ECAN1 Transmit Data Request
79	71	0x0000A2	0x0001A2	C2TX – ECAN2 Transmit Data Request
80-125	72-117	0x0000A4-0x0000FE	0x0001A4-0x0001FE	Reserved

TABLE 7-2: TRAP VECTORS

Vector Number	IVT Address	AIVT Address	Trap Source
0	0x000004	0x000104	Reserved
1	0x000006	0x000106	Oscillator Failure
2	0x000008	0x000108	Address Error
3	0x00000A	0x00010A	Stack Error
4	0x00000C	0x00010C	Math Error
5	0x00000E	0x00010E	DMA Error Trap
6	0x000010	0x000110	Reserved
7	0x000012	0x000112	Reserved

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B enabled
0 = Trap disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Arithmetic Error Status bit
1 = Math error trap was caused by a divide by zero
0 = Math error trap was not caused by a divide by zero

bit 5 **DMACERR:** DMA Controller Error Status bit
1 = DMA controller error trap has occurred
0 = DMA controller error trap has not occurred

bit 4 **MATHERR:** Arithmetic Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

REGISTER 7-6: IFS1: INTERRUPT FLAG STATUS REGISTER 1 (CONTINUED)

bit 3	**CNIF:** Input Change Notification Interrupt Flag Status bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 2	**Unimplemented:** Read as ‘0’
bit 1	**MI2C1IF:** I2C1 Master Events Interrupt Flag Status bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred
bit 0	**SI2C1IF:** I2C1 Slave Events Interrupt Flag Status bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred

REGISTER 8-2: DMAxREQ: DMA CHANNEL x IRQ SELECT REGISTER

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
FORCE(1)	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IRQSEL6(2)	IRQSEL5(2)	IRQSEL4(2)	IRQSEL3(2)	IRQSEL2(2)	IRQSEL1(2)	IRQSEL0(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FORCE:** Force DMA Transfer bit(1)
1 = Force a single DMA transfer (Manual mode)
0 = Automatic DMA transfer initiation by DMA request

bit 14-7 **Unimplemented:** Read as ‘0’

bit 6-0 **IRQSEL<6:0>:** DMA Peripheral IRQ Number Select bits(2)
1111111 = DMAIRQ127 selected to be Channel DMAREQ
•
•
•
0000000 = DMAIRQ0 selected to be Channel DMAREQ

Note 1: The FORCE bit cannot be cleared by the user. The FORCE bit is cleared by hardware when the forced DMA transfer is complete.
2: Please see Table 8-1 for a complete listing of IRQ numbers for all interrupt sources.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER[1,3] (CONTINUED)

bit 1 **LPOSCEN:** Secondary (LP) Oscillator Enable bit
1 = Enable secondary oscillator
0 = Disable secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Request oscillator switch to selection specified by NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This is register is reset only on a Power-on Reset (POR).

10.2.2 IDLE MODE

Idle mode has these features:

- The CPU stops executing instructions
- The WDT is automatically cleared
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active

The device will wake from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the PWRSAV instruction, or the first instruction in the ISR.

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

10.3 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

It is also possible to use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is now placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled via the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers will have no effect and read values will be invalid.

A peripheral module is only enabled if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of 1 instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of 1 instruction cycle (assuming the module control registers are already configured to enable module operation).

Note: The buffers, SID, EID, DLC, Data Field and Receive Status registers are located in DMA RAM.

REGISTER 19-27: CiTRBnSID: ECAN™ BUFFER n STANDARD IDENTIFIER (n = 0, 1, ..., 31)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID<10:6>				
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID<5:0>						SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit
1 = Message will request remote transmission
0 = Normal message

bit 0 **IDE:** Extended Identifier bit
1 = Message will transmit extended identifier
0 = Message will transmit standard identifier

REGISTER 19-28: CiTRBnEID: ECAN™ BUFFER n EXTENDED IDENTIFIER (n = 0, 1, ..., 31)

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID<17:14>			
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<13:6>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-0 **EID<17:6>:** Extended Identifier bits

REGISTER 21-5: ADxCHS123: ADCx INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NB<1:0>		CH123SB
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NA<1:0>		CH123SA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-9 **CH123NB<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample B bits

When AD12B = 1, CHxNB is: U-0, Unimplemented, Read as ‘0’
11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11
10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8
0x = CH1, CH2, CH3 negative input is VREF-

bit 8 **CH123SB:** Channel 1, 2, 3 Positive Input Select for Sample B bit

When AD12B = 1, CHxSB is: U-0, Unimplemented, Read as ‘0’
1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5
0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-1 **CH123NA<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample A bits

When AD12B = 1, CHxNA is: U-0, Unimplemented, Read as ‘0’
11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11
10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8
0x = CH1, CH2, CH3 negative input is VREF-

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample A bit

When AD12B = 1, CHxSA is: U-0, Unimplemented, Read as ‘0’
1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5
0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

25.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJXXXGPX06A/X08A/X10A electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33FJXXXGPX06A/X08A/X10A family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(4) .... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$(4) .... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} < 3.0V$(4) .... -0.3V to 3.6V
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin(2) .... 250 mA
Maximum current sourced/sunk by any 2x I/O pin(3) .... 8 mA
Maximum current sourced/sunk by any 4x I/O pin(3) .... 15 mA
Maximum current sourced/sunk by any 8x I/O pin(3) .... 25 mA
Maximum current sunk by all ports .... 200 mA
Maximum current sourced by all ports(2) .... 200 mA

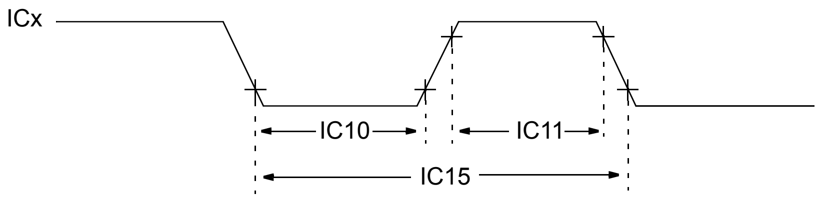
Note 1: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 25-2).

3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the V_{REF+}, V_{REF-}, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.

4: See the **"Pin Diagrams"** section for 5V tolerant pins.

FIGURE 25-6: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



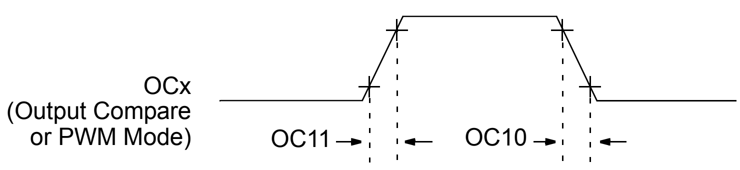
Note: Refer to Figure 25-1 for load conditions.

TABLE 25-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 25-7: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 25-1 for load conditions.

TABLE 25-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter D032
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter D031

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 25-22: DCI MODULE (AC-LINK MODE) TIMING CHARACTERISTICS

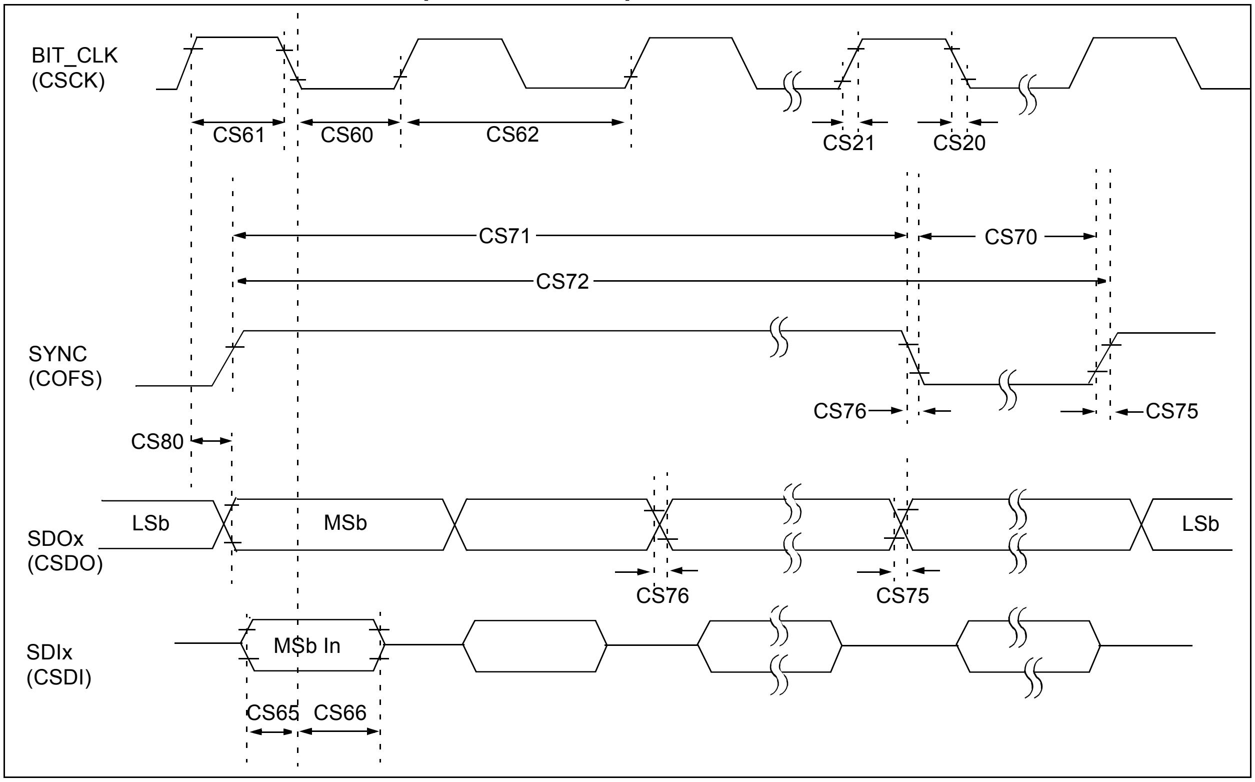


TABLE 25-39: DCI MODULE (AC-LINK MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1,2)**	**Min**	**Typ(3)**	**Max**	**Units**	**Conditions**
CS60	TBCLKL	BIT_CLK Low Time	36	40.7	45	ns	—
CS61	TBCLKH	BIT_CLK High Time	36	40.7	45	ns	—
CS62	TBCLK	BIT_CLK Period	—	81.4	—	ns	Bit clock is input
CS65	TSACL	Input Setup Time to Falling Edge of BIT_CLK	—	—	10	ns	—
CS66	THACL	Input Hold Time from Falling Edge of BIT_CLK	—	—	10	ns	—
CS70	TSYNCLO	SYNC Data Output Low Time	—	19.5	—	µs	**Note 1**
CS71	TSYNCHI	SYNC Data Output High Time	—	1.3	—	µs	**Note 1**
CS72	TSYNC	SYNC Data Output Period	—	20.8	—	µs	**Note 1**
CS75	TRACL	Rise Time, SYNC, SDATA_OUT	—	10	25	ns	CLOAD = 50 pF, VDD = 5V
CS76	TFACL	Fall Time, SYNC, SDATA_OUT	—	10	25	ns	CLOAD = 50 pF, VDD = 5V
CS77	TRACL	Rise Time, SYNC, SDATA_OUT	—	—	30	ns	CLOAD = 50 pF, VDD = 3V
CS78	TFACL	Fall Time, SYNC, SDATA_OUT	—	—	30	ns	CLOAD = 50 pF, VDD = 3V
CS80	TOVDACL	Output Valid Delay from Rising Edge of BIT_CLK	—	—	15	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: These values assume BIT_CLK frequency is 12.288 MHz.

3: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

26.1 High Temperature DC Characteristics

TABLE 26-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33FJXXXGPX06A/X08A/X10A
HDC5	V_{BOR} to 3.6V(1)	-40°C to +150°C	20

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 25-11 for the minimum and maximum BOR values.

TABLE 26-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+155	°C
Operating Ambient Temperature Range	T_A	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $I/O = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 26-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	**Supply Voltage**						
	V_{DD}	—	3.0	3.3	3.6	V	-40°C to +150°C

TABLE 26-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature			
Parameter No.	Typical	Max	Units	Conditions		
Power-Down Current (I_{PD})						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current(1,3)

Note 1: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to V_{SS}. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 26-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

27.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 27-1: VOH – 2x DRIVER PINS

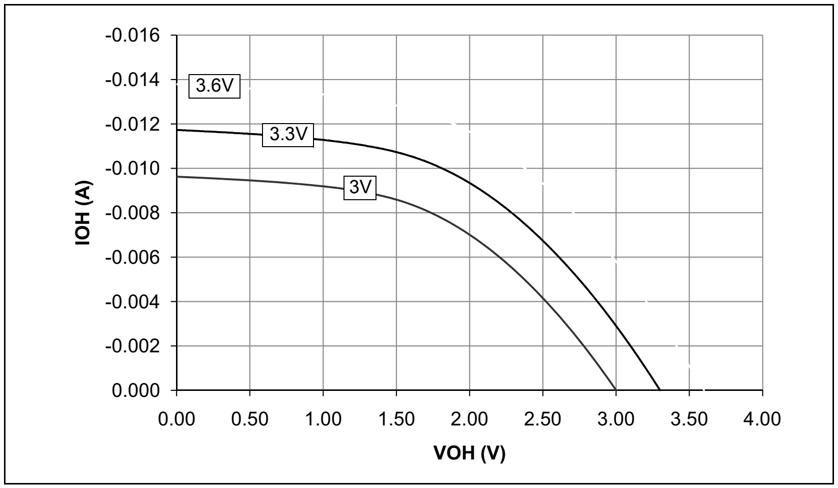


FIGURE 27-2: VOH – 4x DRIVER PINS

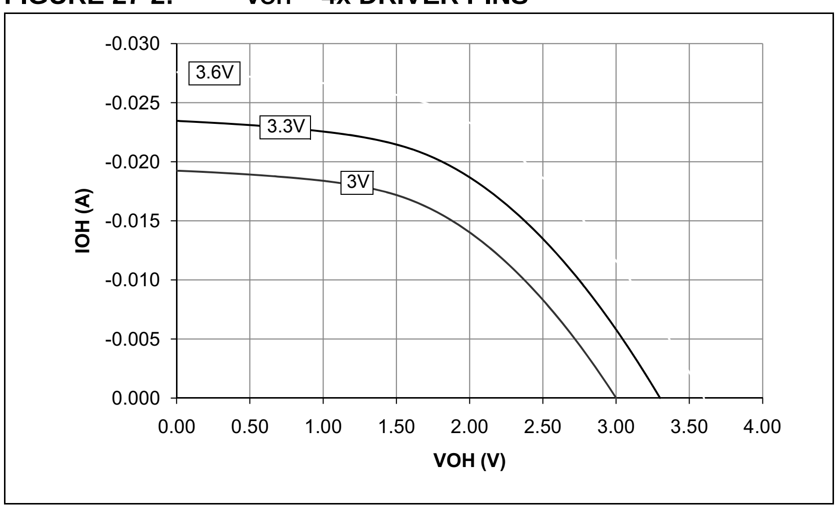


FIGURE 27-3: VOH – 8x DRIVER PINS

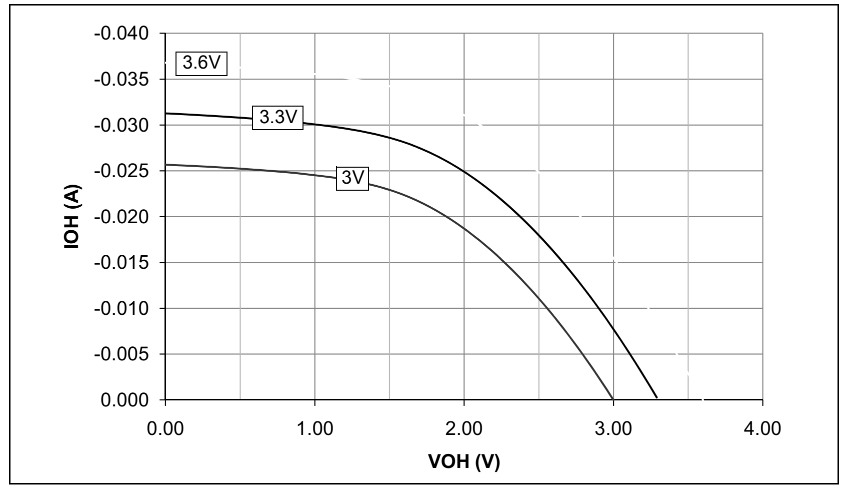
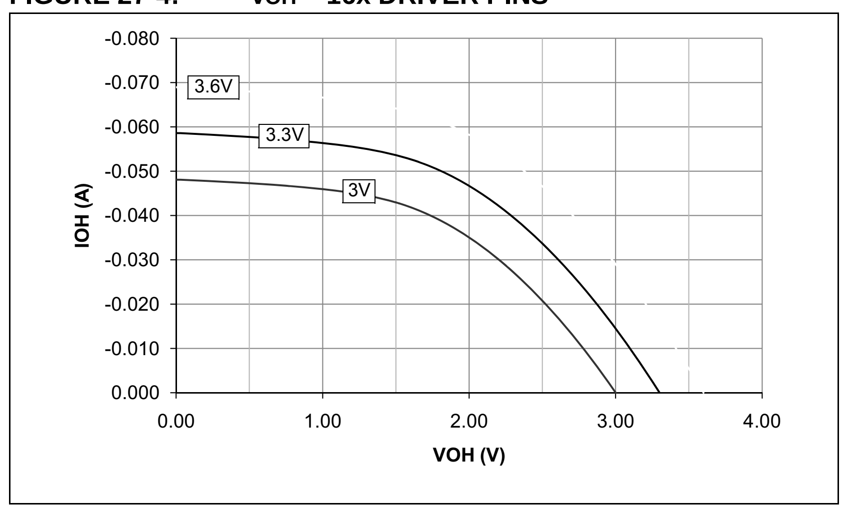
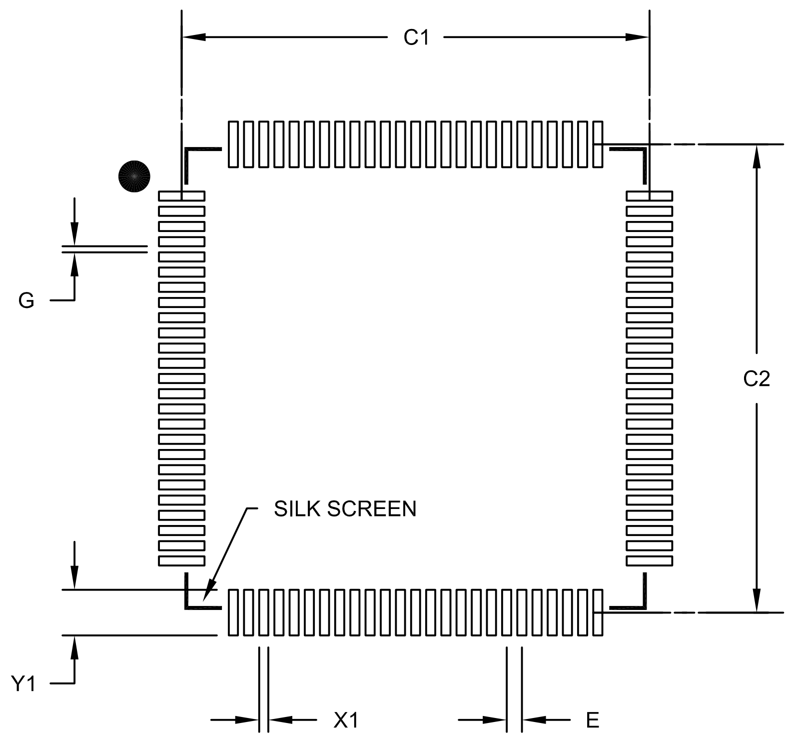


FIGURE 27-4: VOH – 16x DRIVER PINS



100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS	
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B